

描述 / Descriptions

SOT-323 塑封封装 NPN 半导体三极管。Silicon NPN transistor in a SOT-323 Plastic Package.

特征 / Features

电容小,噪声系数低,特征频率高。

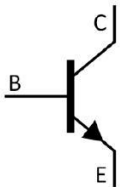
Small feedback capacitance, low noise figure, high f_T .

用途 / Applications

用于信号频率高达 2GHz 的低噪声小信号放大。

Low noise small signal amplifiers up to 2 GHz.

内部等效电路 / Equivalent Circuit



引脚排列 / Pinning



PIN1 : Emitter

PIN 2 : Base

PIN 3 : Collector

印章代码 / Marking

h_{FE} Range	65~150
Marking	HWV2

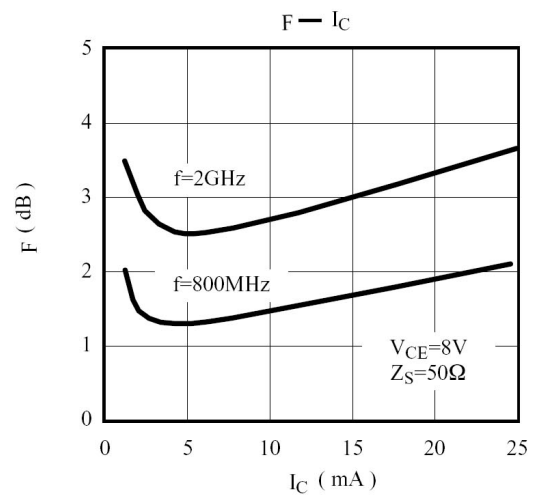
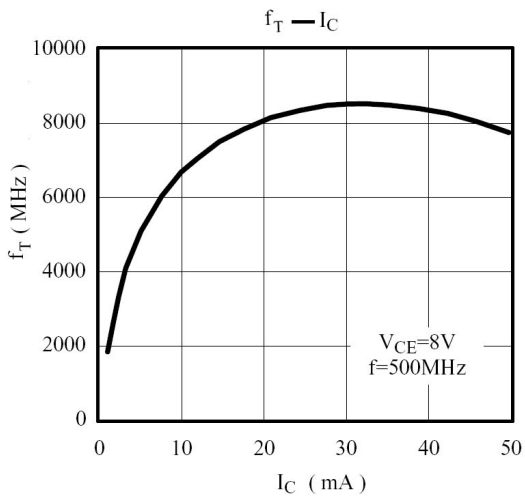
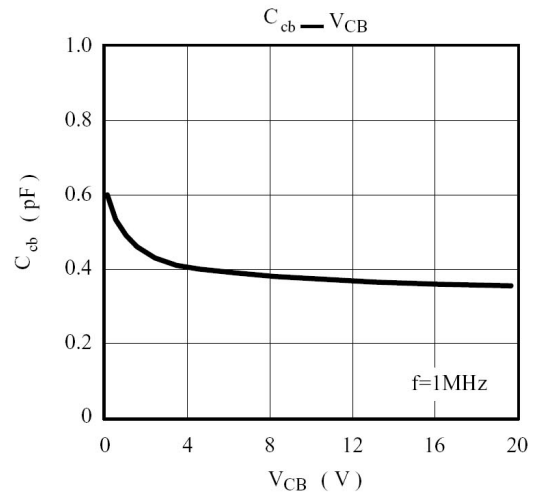
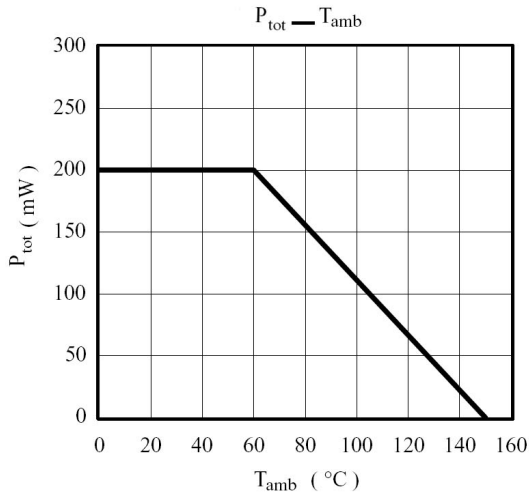
极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Collector to Base Voltage	V_{CBO}	20	V
Collector to Emitter Voltage	V_{CEO}	10	V
Emitter to Base Voltage	V_{EBO}	2.5	V
Collector Current - Continuous	I_C	50	mA
Collector Power Dissipation	P_C	200	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55~150	°C

电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	最小值 Min	典型值 Typ	最大值 Max	单位 Unit
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=1.0mA$ $I_B=0$	10			V
Collector cut-off current	I_{CES}	$V_{CE}=20V$ $V_{BE}=0$			100	μA
Collector Cut-Off Current	I_{CBO}	$V_{CB}=15V$ $I_E=0$			0.1	μA
Emitter Base Cut-Off Current	I_{EBO}	$V_{EB}=1.0V$ $I_C=0$			1.0	μA
DC Current Gain	h_{FE}	$V_{CE}=5.0V$ $I_C=15mA$	65	100	150	
Collector to Emitter Saturation Voltage	$V_{CE(sat)}$	$I_C=50mA$ $I_B=5.0mA$		0.1	0.4	V
Transition Frequency	f_T	$V_{CE}=8.0V$ $I_C=15mA$ $f=500MHz$		7.5		GHz
Collector-Base Capacitance	C_{Cb}	$V_{CB}=10V$ $f=1.0MHz$		0.4		pF
Collector-Emitter Capacitance	C_{Ce}	$V_{CE}=8.0V$ $f=1.0MHz$		0.2		pF
Emitter-Base Capacitance	C_{eb}	$V_{EB}=0.5V$ $f=1.0MHz$		0.85		pF
Noise Figure	NF	$V_{CE}=8.0V$ $I_C=15mA$ $Z_s=50\Omega$ $f=2GHz$		2.5		dB

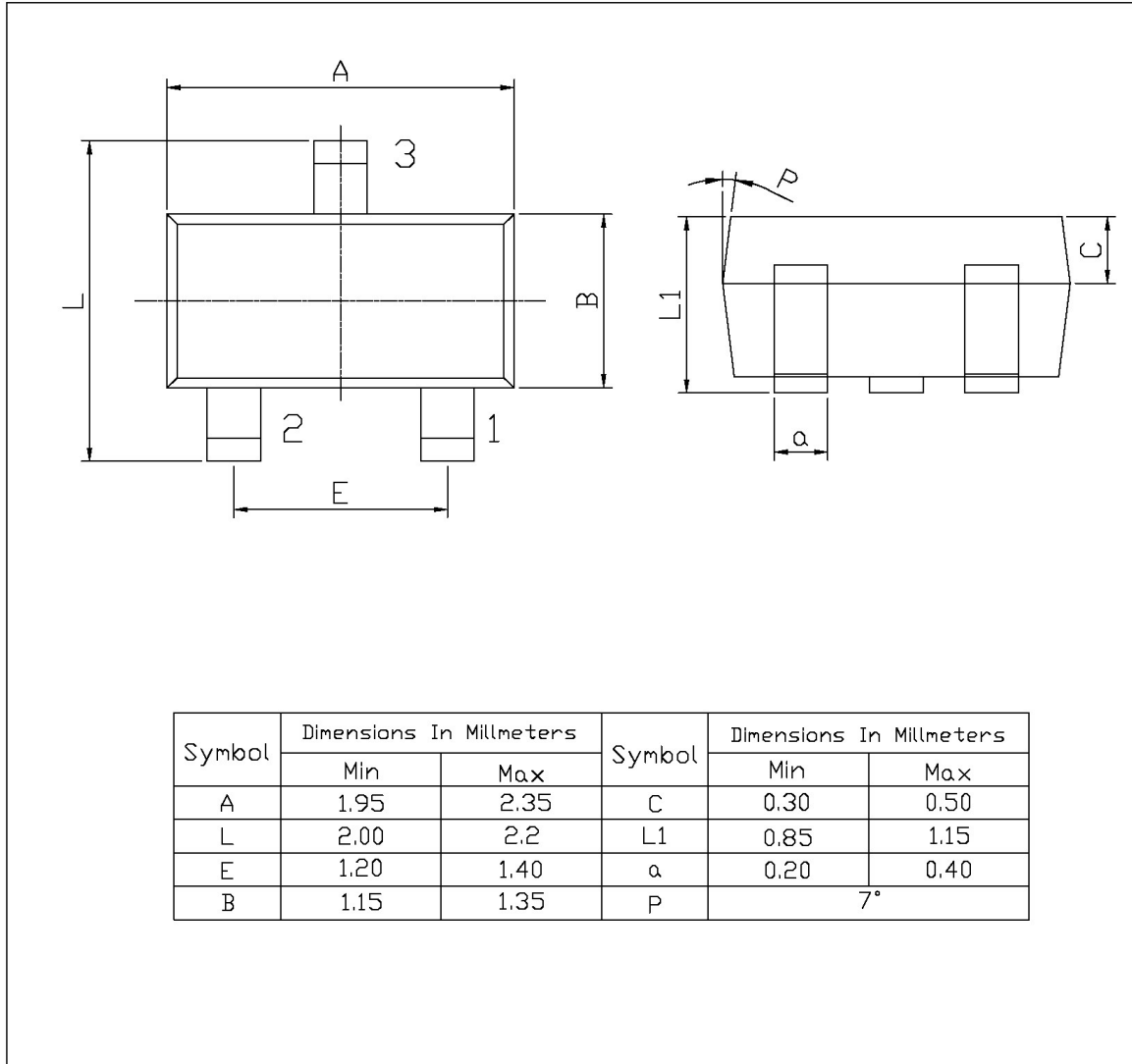
电参数曲线图 / Electrical Characteristic Curve



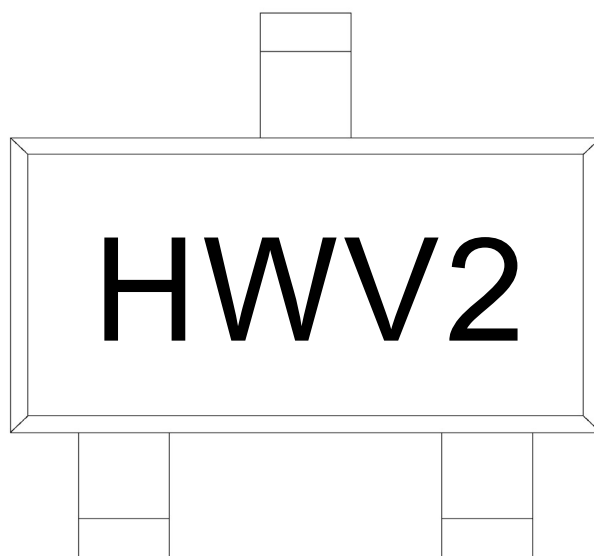
外形尺寸图 / Package Dimensions

SOT-323

单位: mm



印章说明 / Marking Instructions



说明：

H： 为公司代码

WV2： 为型号代码

Note:

H: Company Code.

WV2: Product Type.

回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)



说明：

- 1、预热温度 25~150°C，时间 60~90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：260±5°C 时间：10±1 sec. Temp.:260±5°C Time:10±1 sec

包装规格 / Packaging SPEC.

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-323	3,000	10	30,000	6	180,000	7" x8	180×120×180	390×385×205

使用说明 / Notices